

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00401	1.37	0.06028
	Doped silicon	Silicon (Si)	7440-21-3	0.2888	98.63	4.33972
Subtotal				0.29281	100	4.4
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.00665	10.0	0.1
	Silver alloy	Silver (Ag)	7440-22-4	0.00133	2.0	0.02
	Lead alloy	Lead (Pb)	7439-92-1	0.05856	88.0	0.88
Subtotal				0.06654	100	1
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.28005	100.0	4.20829
Subtotal				0.28005	100	4.20829
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00978	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00652	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00978	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03585	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.53232	99.81	488.8594
Subtotal				32.59425	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32275	100.0	4.85
Subtotal				0.32275	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.31549	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.81931	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46511	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19933	0.3	2.99532
	Polymer	Epoxy resin system		6.64436	10.0	99.844
Subtotal				66.4436	100	998.44
Total				100	100	1502.6883

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